

ABSTRACT

To provide a film which is excellent in releasing property with respect to a resin sealed portion and excellent in low migration property and peeling property with respect to a semiconductor chip, a source electrode or a sealing glass and which is suitable as a mold release film for producing a semiconductor element having a part of the surface of a semiconductor chip, source electrode or sealing glass exposed. A film 1 which comprises a substrate 3 and an adhesive layer 5, wherein the storage elastic modulus at 180°C of the substrate 3 is from 10 to 100 MPa, and the adhesive layer 5 is a reaction cured product of a composition for adhesive layer comprising a specific acrylic polymer and a polyfunctional isocyanate compound, wherein the number of moles M_{OH} of hydroxy groups and the number of moles M_{COOH} of carboxy groups, derived from the acrylic polymer, and the number of moles M_{NCO} of isocyanate groups derived from the polyfunctional isocyanate compound, satisfy a specific relation, and which is suitable as a mold release film for producing a semiconductor element.